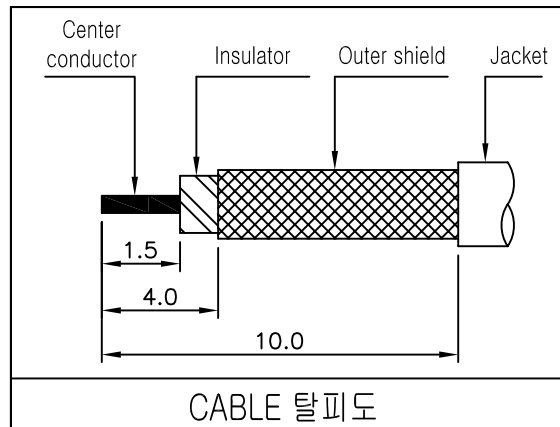
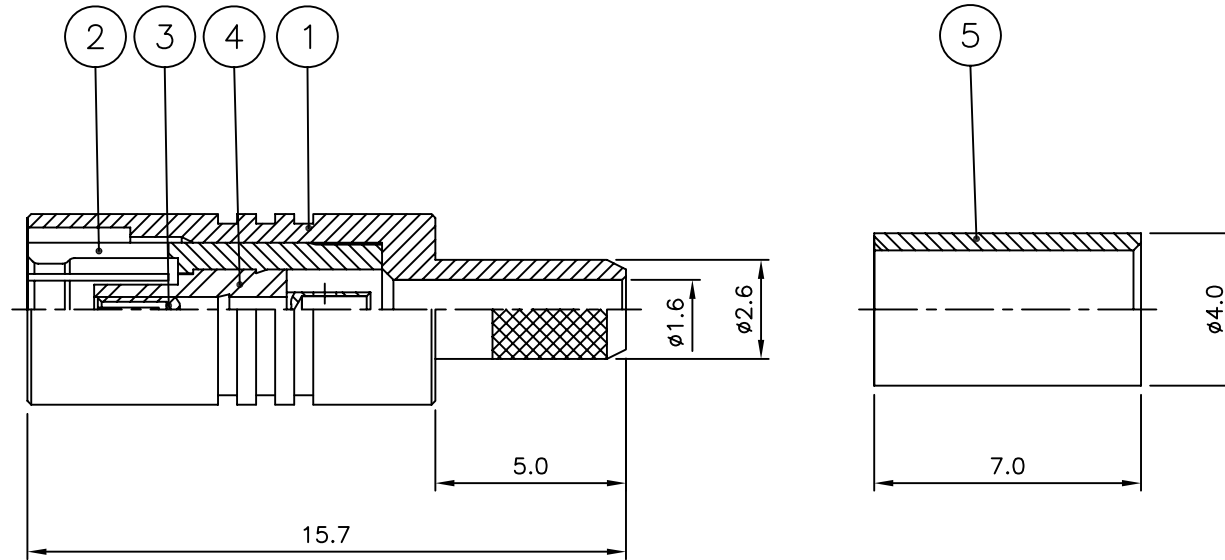


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	H.J.LEE	I.C.KIM	2016.07.22.



- * 조립순서
 1. 2번 JACK에 4번 TEFLON을 조립한다.
 2. 1번 BODY에 2번 JACK을 억지끼움 한다.
 (JACK 조립시 CEQ00451-N/1 정해진 JIG 사용하여 조립한다.)

5	FERRULE	1	MBsBD C3604BD-F	Nickel Plate	DFE00179-5/1
4	INSULATOR	1	TEFLON		DIN02808-N/1
3	CONTACT	1	BeCu C17300	Gold Plate	DCT03736-5/1
2	JACK	1	BeCu C17300	Nickel Plate	DJA00231-5/1
1	BODY(A)	1	MBsBD C3604BD-F	Nickel Plate	DBD04203-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2016. 07. 22.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY		TITLE MMBL50 CABLE JS RG316(50Ω)
		DRAWN BY	H.J.LEE	
FINISH		SCALE	5/1	DWG NO. CN03637-7/1 REVISION I R SHEET 1 of 1
		UNIT	mm	